TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π–MOSV)

# 2SK2493

### Chopper Regulator and DC-DC Converter Applications

Unit: mm

• 2.5-V gate drive

• Low drain-source ON resistance :  $RDS(ON) = 0.08 \text{ m}\Omega \text{ (typ.)}$ 

• High forward transfer admittance  $|Y_{fs}| = 8.0 \text{ S (typ.)}$ 

• Low leakage current  $: IDSS = 100 \mu A \text{ (max) (VDS} = 16 \text{ V)}$ 

• Enhancement mode :  $V_{th} = 0.5 \sim 1.1 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA)}$ 

### Absolute Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Drain-source voltage		$V_{DSS}$	16	V	
Drain-gate voltage (R <sub>GS</sub> = 20 kΩ)		$V_{DGR}$	16	V	
Gate-source voltage		$V_{GSS}$	±8	V	
Drain current	DC (Note 1)	I <sub>D</sub>	5	Α	
	Pulse (Note 1)	I <sub>DP</sub>	20	Α	
Drain power dissipation (Tc = 25°C)		$P_{D}$	20	W	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature range		T <sub>stg</sub>	-55~150	°C	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

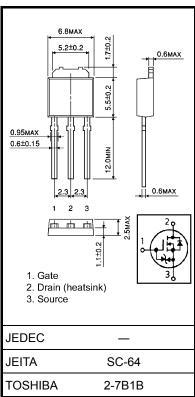
#### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R <sub>th (ch-c)</sub>	6.25	°C/W
Thermal resistance, channel to ambient	R <sub>th (ch-a)</sub>	125	°C/W

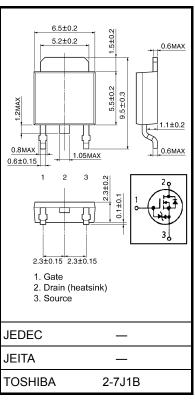
Note 1: Ensure that the channel temperature does not exceed 150°C.

This transistor is an electrostatic-sensitive device.

Please handle with caution.



Weight: 0.36 g (typ.)



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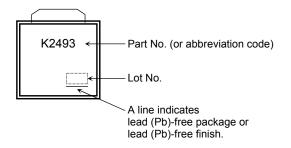
## **Electrical Characteristics (Ta = 25°C)**

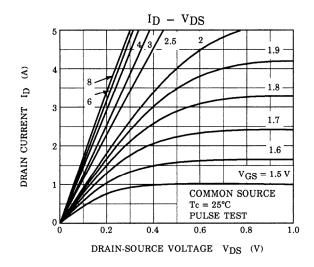
Charac	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit	
Gate leakage cu	ırrent	I <sub>GSS</sub>	V <sub>GS</sub> = ±6.5 V, V <sub>DS</sub> = 0 V	_	_	±10	μΑ	
Drain cut-off cu	rrent	I <sub>DSS</sub>	V <sub>DS</sub> = 16 V, V <sub>GS</sub> = 0 V	_	_	100	μA	
Drain-source br	reakdown voltage	V (BR) DSS	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	16	_	_	V	
Gate threshold v	oltage/	$V_{th}$	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	0.5	_	1.1	V	
Drain-source ON resistance		R <sub>DS (ON)</sub>	V <sub>GS</sub> = 2.5 V, I <sub>D</sub> = 2.5 A	_	0.08	0.12	Ω	
			V <sub>GS</sub> = 4 V, I <sub>D</sub> = 2.5 A	_	0.07	0.1		
Forward transfer	r admittance	Y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 2.5 A	4.0	8.0	_	S	
Input capacitano	e	C <sub>iss</sub>		_	1200	_		
Reverse transfer capacitance		C <sub>rss</sub>	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	110	_	pF	
Output capacitance		Coss		_	380	_		
Switching time	Rise time	t <sub>r</sub>	$V_{GS} \stackrel{5V}{\underset{0V}{\bigvee}} \stackrel{I_{D}=2.5A}{\underset{R_{L}=}{\bigvee}} V_{OUT}$	_	30	_		
	Turn-on time	t <sub>on</sub>		_	50	_	no	
	Fall time	t <sub>f</sub>		_	200	_	- ns	
	Turn-off time	t <sub>off</sub>	$V_{DD} = 8V$ Duty $\leq 1\%$ , $t_W = 10 \mu s$	_	650	_		
Total gate charge (Gate-source plus gate-drain)		Qg		_	23	_		
Gate-source charge		Q <sub>gs</sub>	$V_{DD} \approx 16 \text{ V}, V_{GS} = 5 \text{ V}, I_{D} = 5 \text{ A}$		17	_	nC	
Gate-drain ("miller") charge		$Q_{gd}$			6	_		

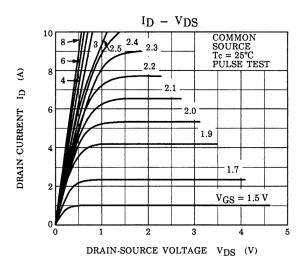
### **Source-Drain Ratings and Characteristics (Ta = 25°C)**

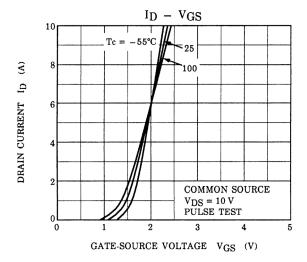
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I <sub>DR</sub>	_	_	_	5	Α
Pulse drain reverse current (Note 1)	I <sub>DRP</sub>	_	_	_	20	Α
Forward voltage (diode)	V <sub>DSF</sub>	I <sub>DR</sub> = 5 A, V <sub>GS</sub> = 0 V	_	_	-1.7	V
Reverse recovery time	t <sub>rr</sub>	I <sub>DR</sub> = 5 A, V <sub>GS</sub> = 0 V	1	120	1	ns
Reverse recovery charge	Q <sub>rr</sub>	dI <sub>DR</sub> / dt = 50 Å / μs	_	0.12	_	μC

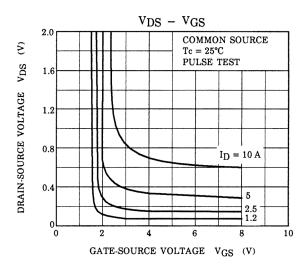
## Marking

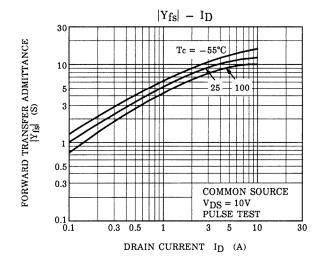


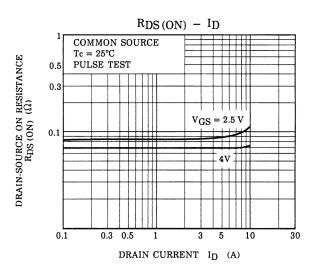




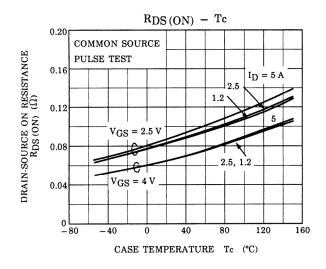


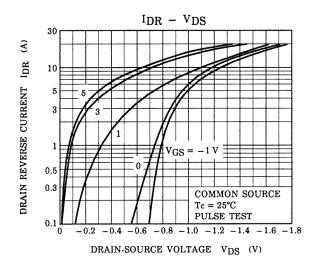


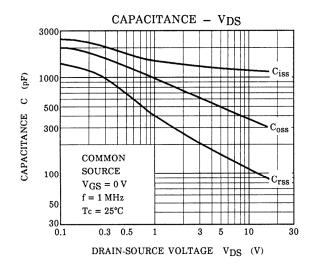


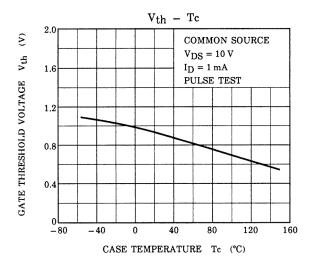


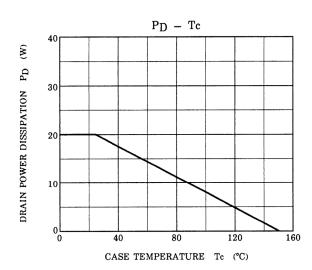
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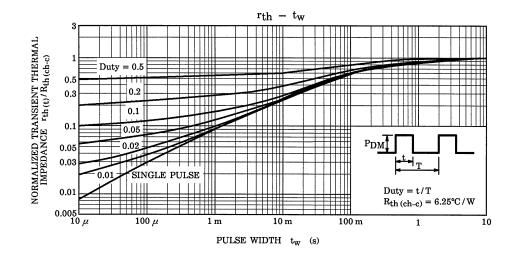


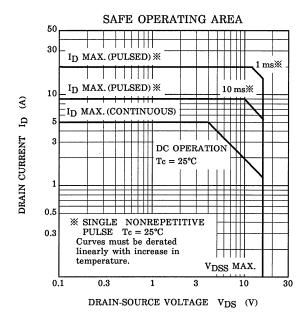












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